

CERAMIC SURFACE MOUNT PIN DIODE

DESCRIPTION

With high isolation, low loss, and low distortion characteristics, this Microsemi ceramic package PIN diode is perfect for two-way radio antenna switch applications where size and power handling capability are critical.

Its advantages also include the low forward bias resistance and high zero bias impedance that are essential for low loss, high isolation, and wide bandwidth antenna switch performance. Its square design makes this device ideal for use with automatic insertion equipment.

KEY FEATURES

- High power surface mount package
- Specified low distortion, low loss
- Low bias current requirements
- High zero bias impedance
- Very low inductance and capacitance
- Passivated PIN diode chip
- Hermetically sealed
- Compatible with automatic insertion equipment

IMPORTANT: For the most current data, consult *MICROSEMI*'s website: http://www.microsemi.com

ABSOLUTE MAXIMUM RATINGS AT 25° C (UNLESS OTHERWISE SPECIFIED)					
Maximum reverse voltage	50 V				
Average power dissipation contact surfaces @ 25 °C	4.0 W				
Thermal resistance 25 °C Contacts Free Air	37.5 ^O C/W 1.5 W				
Operating and storage temperature	-65 °C to +175 °C				

APPLICATIONS/BENEFITS

RoHS compliant packaging available: use UMX9401F





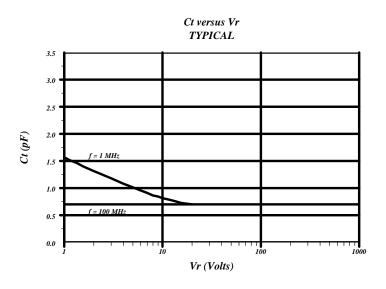
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Parameter	Symbol	Conditions	Min	Тур.	Max	Units
Series resistance	Rs	F = 100 MHz I _F = 50 mA		0.5	0.75	Ohms
Capacitance	Ст	F = 1 MHz, V _R = 50 V		0.75	0.90	pF
Parallel resistance	R _P	F = 100 MHz, V _R = 0 V	5k	10k		Ohms
Carrier lifetime	τ	I _F = 10 mA	2.0	4.0		μS
Transmit Harmonic distortion		P _{IN} = 50 W F = 50 MHz I _F = 50 mA	80			-dB
Receive 3rd order harmonic distortion		F = 100 MHz V = 0 V F _A = 50 MHz F _B = 51 MHz	60			-dB
Voltage rating	V _R	Ι _R = 1 μΑ	50			V
Forward Voltage	V _F	I _F = 100 mA			1.0	V

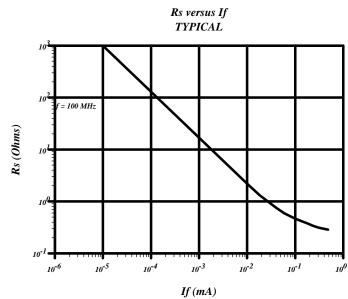
UM9401F



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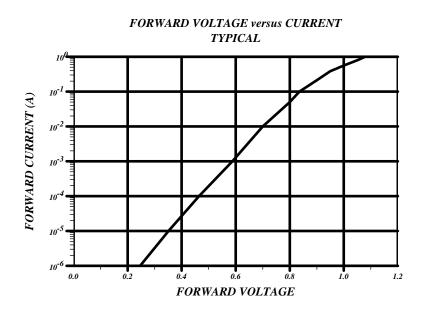
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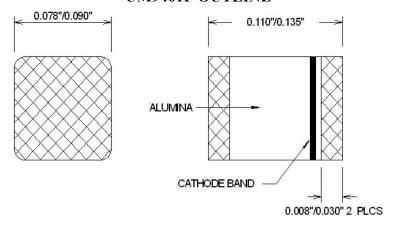
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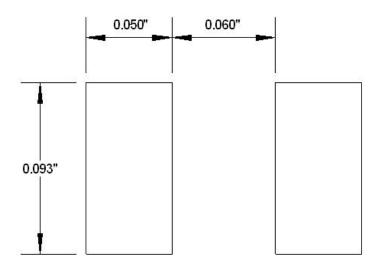
UM9401F OUTLINE



UM9401F FOOTPRINT



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NOTES:

- 1. These dimensions will match the terminals and provide for additional solder fillets at the outboard ends at Least as wide as the terminals themselves, assuming accuracy of placement within 0.005"
- 2. If the mounting method chosen requires use of an adhesive separate from the solder compound, a round (or square) spot of cement should be centrally located.



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